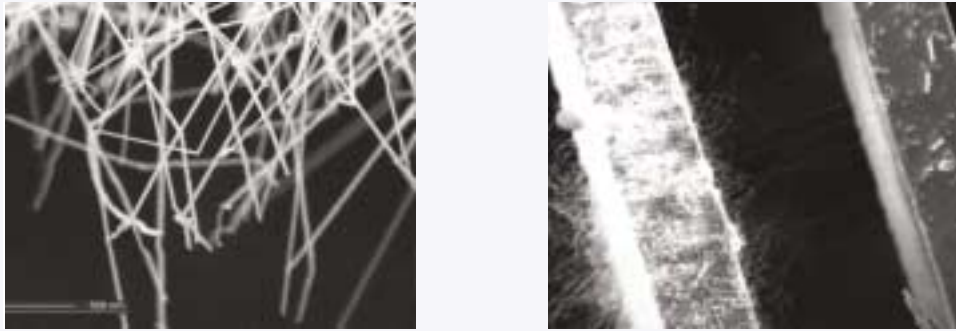


Micro Electromechanical Systems Division (MEMS)

Serving Engineers Around the World in the Micro Electromechanical Systems Areas

Mission Statement

Foster and lead the promotion of miniature devices combining electrical, mechanical, optical, chemical and/or biological components fabricated via integrated circuit or other similar manufacturing techniques

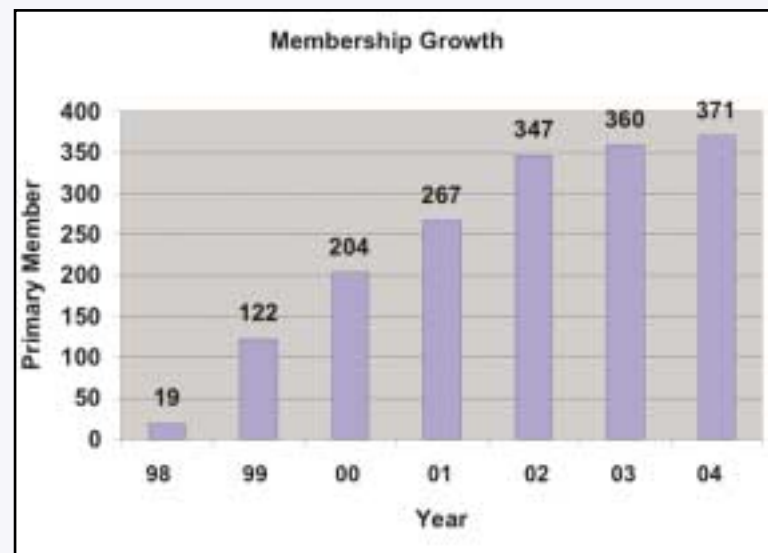


MEMS Division Goals

1. Facilitate interaction and discussion among the MEMS community and generate opportunities for collaboration to spawn creativity
2. Identify the needs and problems of the MEMS community and bring together appropriate people to address them
3. Provide a platform to generate standards and guidelines for MEMS processes and technologies.
4. Educate and inform engineers and scientists in various fields of the ongoing developments in the MEMS field.
5. Train new multi-disciplinary MEMS researchers for furthering the field.

Division's Health

- Fast growth path in the first five year
- Stable growth afterwards
- Competition from the ASME Nanotechnology Institute since 2002



Division History

- 15 consecutive MEMS Symposia were held during the ASME Winter Annual Meetings or International Mechanical Engineering Congress and Expositions since 1990
- Has been a technical panel under the Dynamic System and Control Division before 1998
- MEMS subdivision was established in 1998 based on ASME by-law B5.8.5.
- MEMS division was established in 2004 based on ASME by-law B5.8.6.

Division Major Activities

- IMECE: MEMS is a multi-disciplinary field and the division has been working with other ASME divisions, including Dynamic System and Control, Heat Transfer, Fluids Engineering, Applied Mechanics, Bioengineering, Design Engineering, Electrical and Electronic Packaging, Manufacturing Engineering, etc.
- InterPack 2005: Co-sponsor with EEPD



Growth Potential



Name	Sponsor	Frequency	Attendance
International Conference on Solid-State Sensors and Actuators	IEEE	Every two years	>1000
International Micro Electro Mechanical Systems Conference	IEEE	Every year	>500
Solid-State Sensors and Actuators Workshop Micromachining and Microfabrication	Transducers Foundation SPIE	Every two years	>500
		Every year	>300
Eurosensors	European MST	Every year	>500

Other Programs

- ASME MEMS Technology Seminar
– 5TH year to foster MEMS education and industrial collaborations



Division Journal

- IEEE/ASME Journal of Microelectromechanical is ranked No. 7 out of all IEEE journals in terms of impact factor



Executive Committee

Position	Name	Affiliation
Chair	Liwei Lin	UC-Berkeley
Vice Chair	James Allen	Sandia National Lab
Secretary	Kim Turner	UC-Santa Barbara
IMECE Symposium Chair	Aaron Knobloch	General Electric Inc.
Treasure	Cetin Cetinkaya	Clarkson University

A diverse group of volunteers from University, National Lab and Industry